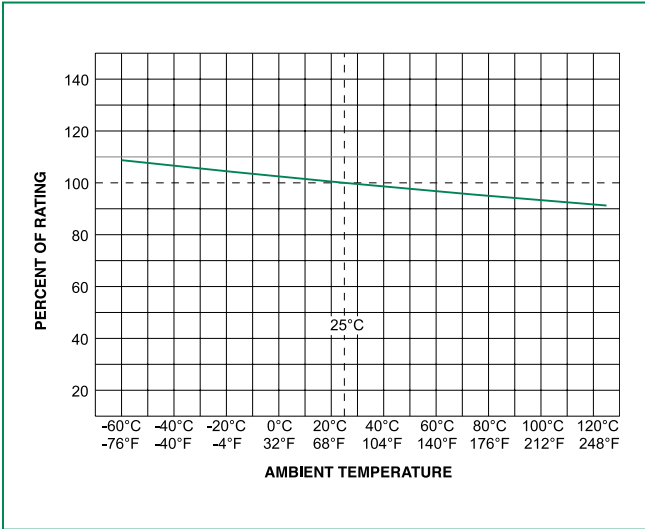
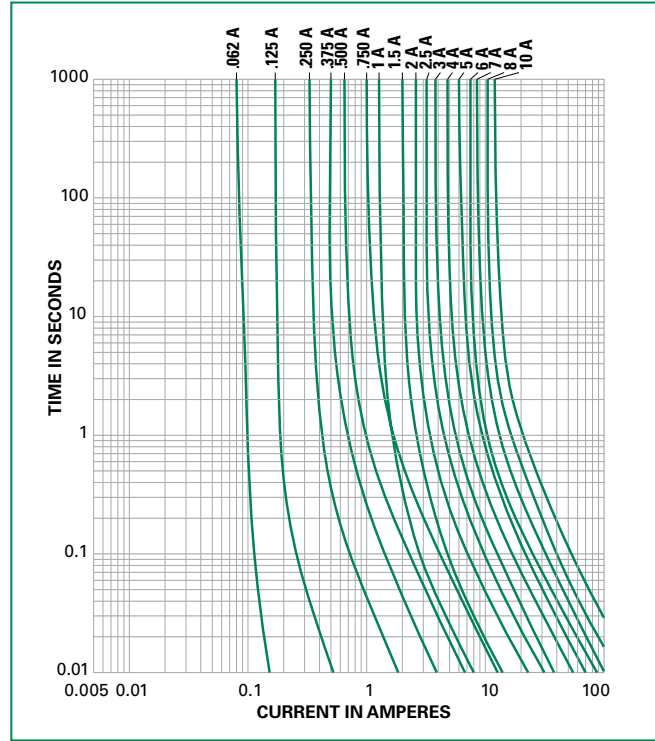


Temperature Re-rating Curve



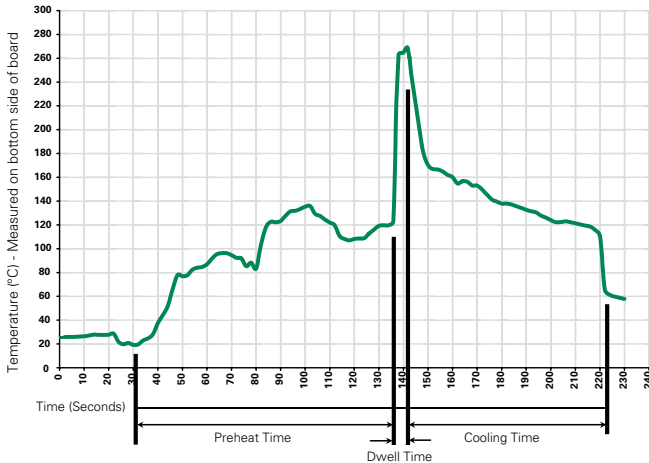
Note:
Rerating depicted in this curve is in addition to the industry practice derating of 25% for continuous operation.

Average Time Current Curves



Please contact Littelfuse for more details on those T-C Curves of other ampere ratings which are not published.

Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C
Heating Time: 5 seconds max.

Note: These devices are not recommended for IR or Convection Reflow process.

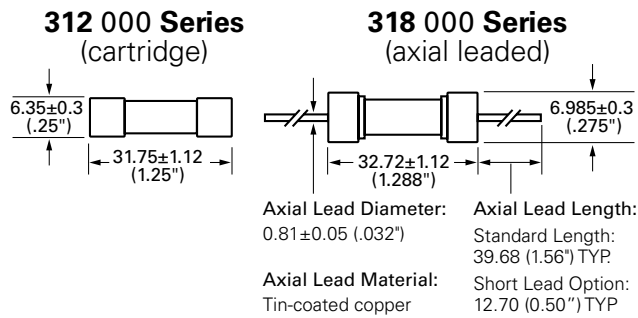
Product Characteristics

Materials	Body: Glass Cap: Nickel-plated brass Leads: Tin-plated Copper
Terminal Strength	MIL-STD-202, Method 211, Test Condition A
Solderability	MIL-STD-202 method 208
Product Marking	Cap1: Brand logo, current and voltage ratings Cap2: Series and agency approval marks

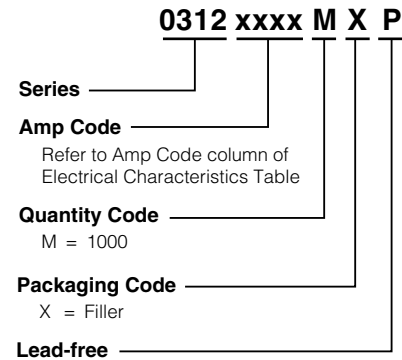
Operating Temperature	-55°C to +125°C
Thermal Shock	MIL-STD-202, Method 107, Test Condition B: (5 cycles -65°C to +125°C)
Vibration	MIL-STD-202, Method 201
Humidity	MIL-STD-202, Method 103, Test Condition A: High RH (95%), and Elevated temperature (40°C) for 240 hours
Salt Spray	MIL-STD-202, Method 101, Test Condition B

Dimensions

Measurements displayed in millimeters (inches)



Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Taping Width
312 Series				
Bulk	N/A	1000	MX	N/A
Bulk	N/A	100	HX	N/A
318 Series				
Bulk	N/A	1000	MX	N/A
Bulk	N/A	100	HX	N/A
Bulk	N/A	1000	MXB	N/A